

Amendments to the Claims:

The text of all pending claims, (including withdrawn claims) is set forth below. Cancelled and not entered claims are indicated with claim number and status only. The claims as listed below show added text with underlining and deleted text with ~~striketrough~~. The status of each claim is indicated with one of (original), (currently amended), (cancelled), (withdrawn), (new), (previously present), or (not entered).

Applicant reserves the right to pursue any cancelled claims at a later date.

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1.-10. (canceled)

11. (currently amended) A repair method for repairing a component having a base material with an oriented microstructure, comprising:

applying a solder in a region of the component to be repaired wherein the solder comprises a constituent whose melting temperature is lower than the melting temperature of the component base material; and

heating the solder ~~with a heat source~~ by directly irradiating the solder with a laser beam;
melting the solder material by the heat source wherein the component base material is not ~~heated~~melted;

choosing a speed of the laser beam relative to the component or a power of the laser beam for generating a temperature gradient in the region of the component to be repaired during the heating step to produce an oriented microstructure in the repaired site which comprises the same oriented microstructure as the surrounding base material.

12. (currently amended) The repair method as claimed in claim 11, wherein the temperature gradient is aligned so that it extends in the direction of the orientation of the oriented microstructure of the component base material.

13. (previously presented) The repair method as claimed in claim 12, wherein the solder comprises a first constituent with a melting temperature lower than a melting temperature of the component base material and a second constituent having a high durability and a melting

temperature greater than the first constituent melting temperature but below the base material melting temperature, and the solder is applied in the region of the component to be repaired such that the proportion of first constituent in the solder is greater in the vicinity of the base material than in a portion of the component to be repaired further away from the base material.

14. (canceled).

15. (canceled).

16. (canceled).

17. (currently amended) The repair method as claimed in claim ~~16~~11, wherein the base material is heat treated during the soldering step.

18. (previously presented) The repair method as claimed in claim 17, wherein the solder is in the form of a powder, paste or film.

19. (previously presented) The repair method as claimed in claim 18, wherein the solder powder is a nanopowder.

20.-25. (canceled)